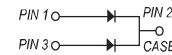
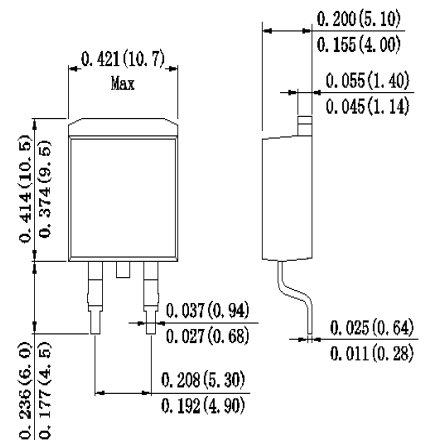


Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Construction utilizes void-free molded plastic technique
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed
250°C/10 seconds at terminals

TO-263



Dimensions in inches and (millimeters)

Mechanical Data

Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MBR 1040CT	MBR 1045CT	MBR 1060CT	MBR 10100CT	MBR 10150CT	MBR 10200CT	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	40	45	60	100	150	200	V
Maximum RMS voltage	V_{RMS}	28	31.5	42	70	105	140	V
Maximum DC blocking voltage	V_{DC}	40	45	60	100	150	200	V
Maximum average forward rectified current at $T_c=110^\circ\text{C}$ per device per diode	$I_{(AV)}$	10.0 5.0						A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	120.0						A
Maximum instantaneous forward voltage per diode at 5.0A	V_F	0.55		0.75	0.85	0.95		V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	I_R	0.5 50			0.05 10			mA
Typical thermal resistance	R_{qJC}	35.0						°C/W
Operating junction temperature range	T_J	-55 to +150						°C
Storage temperature range	T_{STG}	-55 to +150						°C

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

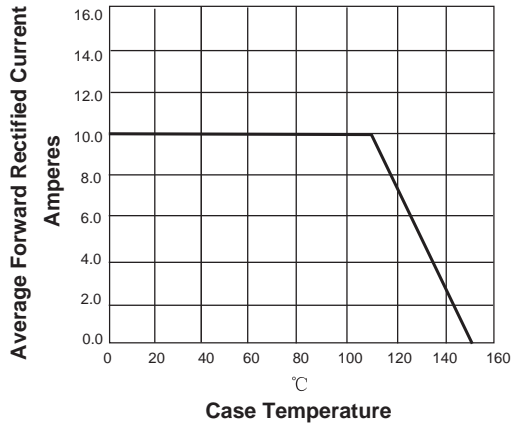


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

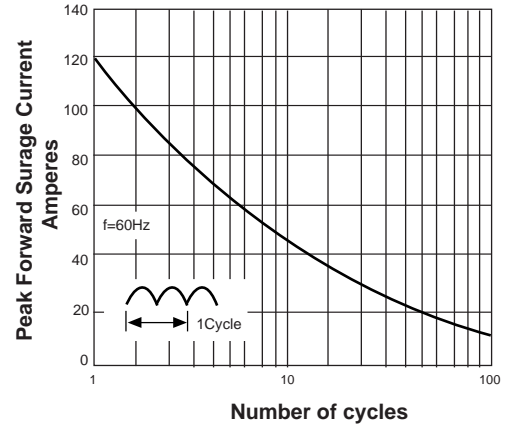


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

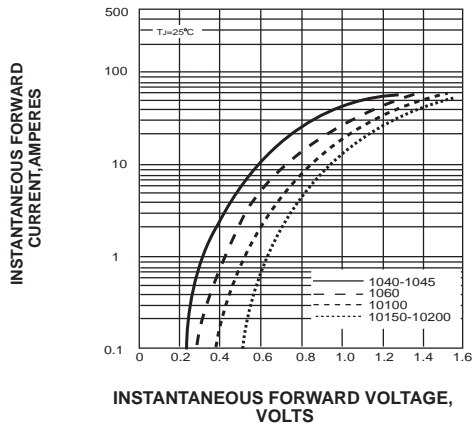
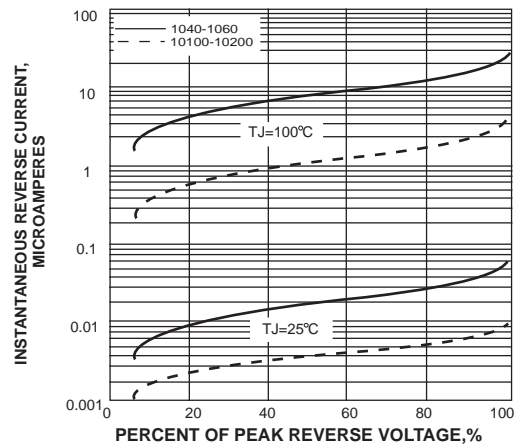
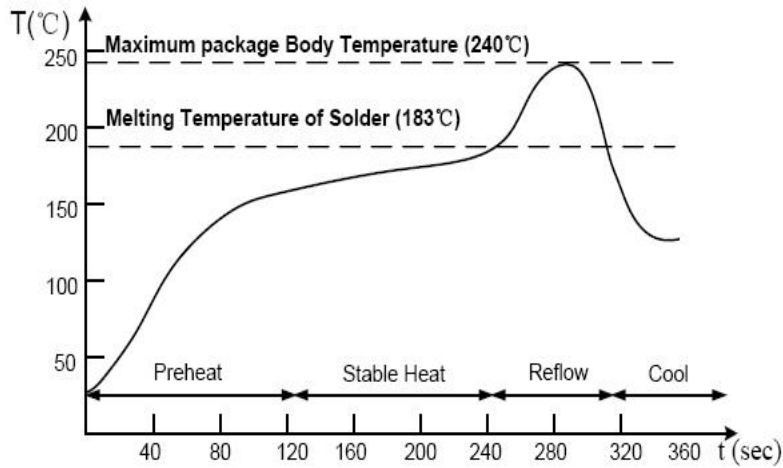


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Suggested Soldering Temperature Profile



Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tube Package

Package	Tube (mm)	Q'TY/Tube (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
TO-263	525*31.9*6.4	0.05	545*150*45	1.0	575*245*170	5.0